



#6 H/W
Docket No.: M1071.1453/P1453 1-2903

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Haruhiko Ikeda

Application No.: 09/927,053

Group Art Unit: 1733

Filed: August 9, 2001

Examiner: Not Yet Assigned

For: METHOD OF BONDING A
CONDUCTIVE ADHESIVE AND AN
ELECTRODE, AND A BONDED
ELECTRODE OBTAINED THEREBY

CHANGE OF CORRESPONDENCE ADDRESS

Commissioner for Patents
Washington, DC 20231

Dear Sir:

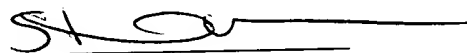
In accordance with the Manual of Patent Examining Procedures, Section 601.03, please change the mailing address for all correspondence in the above-identified patent application to:

Steven I. Weisburd
DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP
1177 Avenue of the Americas
41st Floor
New York, New York 10036-2714
(212) 835-1400

Please direct all further communications to the above-identified firm.

Dated: January 14, 2003

Respectfully submitted,

By 
Steven I. Weisburd
Registration No.: 27,409
1177 Avenue of the Americas
41st Floor
New York, New York 10036-2714
(212) 835-1400
Attorneys for Applicant

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